

N-Channel Power MOSFET

30V, 194A, 1.8mΩ

FEATURES

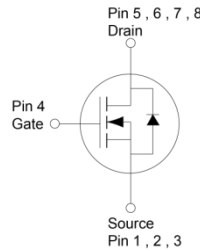
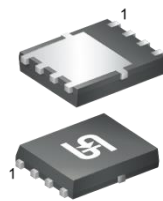
- Low $R_{DS(ON)}$ to minimize conductive losses
- Low gate charge for fast power switching
- 100% UIS and R_g tested
- 175°C Operating Junction Temperature
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

KEY PERFORMANCE PARAMETERS

PARAMETER		VALUE	UNIT
V_{DS}		30	V
$R_{DS(on)}$ (max)	$V_{GS} = 10V$	1.8	mΩ
	$V_{GS} = 4.5V$	2.8	
Q_g		62	nC

APPLICATIONS

- DC-DC Converter
- Battery Management
- Load Switch
- Motor Drive


PDFN56


Note: MSL 1 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current (Note 1)	$T_C = 25^\circ\text{C}$	I_D	194	A
	$T_A = 25^\circ\text{C}$		29	
Pulsed Drain Current		I_{DM}	776	A
Single Pulse Avalanche Current (Note 2)		I_{AS}	52	A
Single Pulse Avalanche Energy (Note 2)		E_{AS}	406	mJ
Total Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	136	W
	$T_C = 125^\circ\text{C}$		45	
Total Power Dissipation	$T_A = 25^\circ\text{C}$	P_D	3.1	W
	$T_A = 125^\circ\text{C}$		1	
Operating Junction and Storage Temperature Range		T_J, T_{STG}	- 55 to +175	$^\circ\text{C}$

THERMAL PERFORMANCE

PARAMETER	SYMBOL	MAXIMUM	UNIT
Junction to Case Thermal Resistance	$R_{\theta JC}$	1.1	$^\circ\text{C/W}$
Junction to Ambient Thermal Resistance	$R_{\theta JA}$	48	$^\circ\text{C/W}$

Thermal Performance Note: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case-thermal reference is defined at the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design. The $R_{\theta JA}$ limit presented here is based on mounting on a 1 in² pad of 2 oz copper.

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV_{DSS}	30	--	--	V
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu A$	$V_{GS(TH)}$	1	1.8	2.5	V
Gate-Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	I_{GSS}	--	--	± 100	nA
Drain-Source Leakage Current	$V_{GS} = 0V, V_{DS} = 30V$	I_{DSS}	--	--	1	μA
	$V_{GS} = 0V, V_{DS} = 30V$ $T_J = 125^{\circ}C$		--	--	100	
Drain-Source On-State Resistance (Note 3)	$V_{GS} = 10V, I_D = 29A$	$R_{DS(on)}$	--	1.4	1.8	m Ω
	$V_{GS} = 4.5V, I_D = 24A$		--	2.1	2.8	
Forward Transconductance (Note 3)	$V_{DS} = 10V, I_D = 29A$	g_{fs}	--	70	--	S
Dynamic (Note 4)						
Total Gate Charge	$V_{GS} = 10V, V_{DS} = 15V,$ $I_D = 29A$	Q_g	--	120	--	nC
Total Gate Charge	$V_{GS} = 4.5V, V_{DS} = 15V,$ $I_D = 24A$	Q_g	--	62	--	
Gate-Source Charge		Q_{gs}	--	21	--	
Gate-Drain Charge		Q_{gd}	--	28	--	
Input Capacitance	$V_{GS} = 0V, V_{DS} = 15V,$ $f = 1.0MHz$	C_{iss}	--	7252	--	pF
Output Capacitance		C_{oss}	--	1056	--	
Reverse Transfer Capacitance		C_{rss}	--	673	--	
Gate Resistance	$f = 1.0MHz$	R_g	0.5	1.8	3.6	Ω
Switching (Note 4)						
Turn-On Delay Time	$V_{GS} = 10V, V_{DS} = 15V,$ $I_D = 29A, R_G = 2\Omega$	$t_{d(on)}$	--	9	--	ns
Turn-On Rise Time		t_r	--	50	--	
Turn-Off Delay Time		$t_{d(off)}$	--	80	--	
Turn-Off Fall Time		t_f	--	45	--	
Source-Drain Diode						
Forward Voltage (Note 3)	$V_{GS} = 0V, I_S = 29A$	V_{SD}	--	--	1	V
Reverse Recovery Time	$I_S = 29A,$	t_{rr}	--	48	--	ns
Reverse Recovery Charge	$di/dt = 100A/\mu s$	Q_{rr}	--	50	--	nC

Notes:

1. Silicon limited current only.
2. $L = 0.3\text{mH}$, $V_{GS} = 10V$, $V_{DD} = 25V$, $R_G = 25\Omega$, $I_{AS} = 52A$, Starting $T_J = 25^\circ\text{C}$
3. Pulse test: Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Switching time is essentially independent of operating temperature.

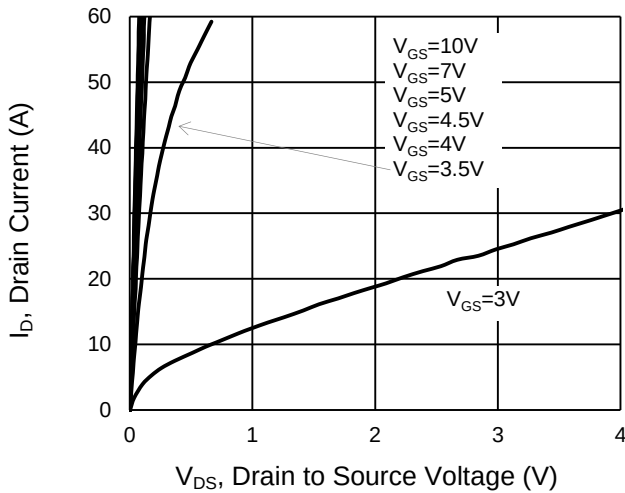
ORDERING INFORMATION

ORDERING CODE	PACKAGE	PACKING
TSM018NB03CR RLG	PDFN56	2,500pcs / 13" Reel

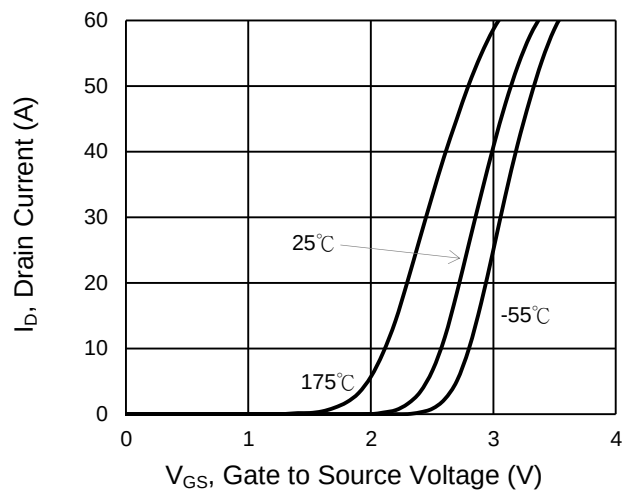
CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

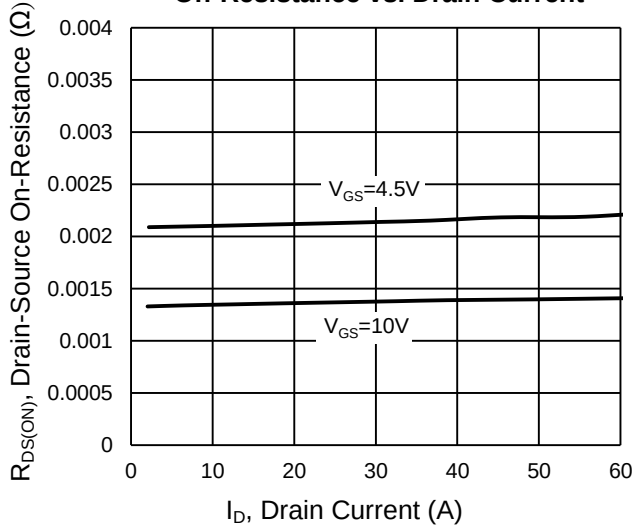
Output Characteristics



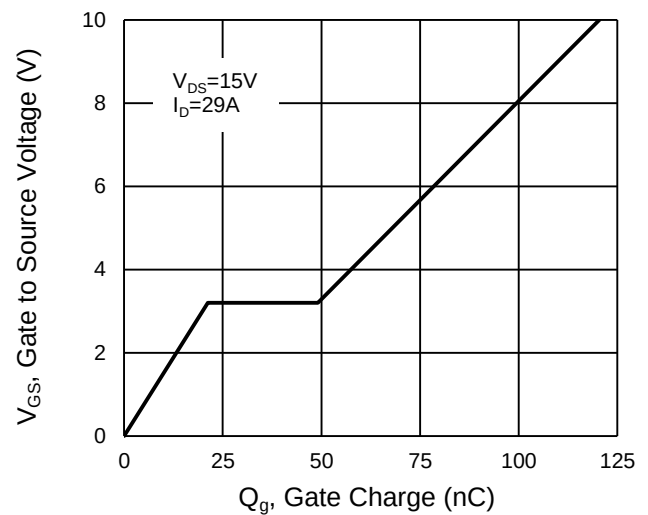
Transfer Characteristics



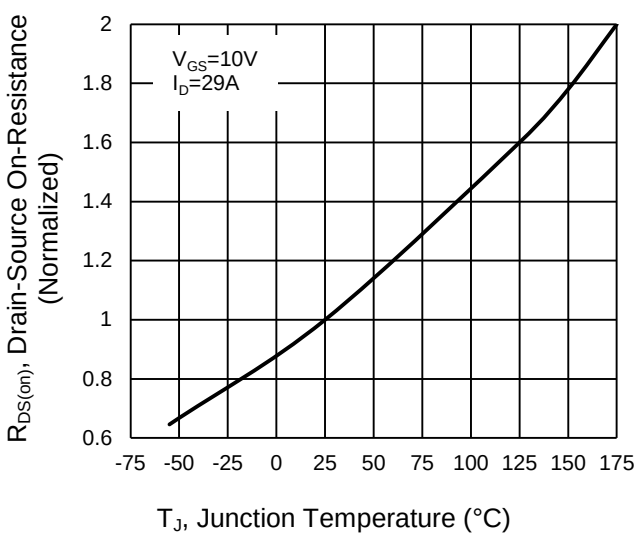
On-Resistance vs. Drain Current



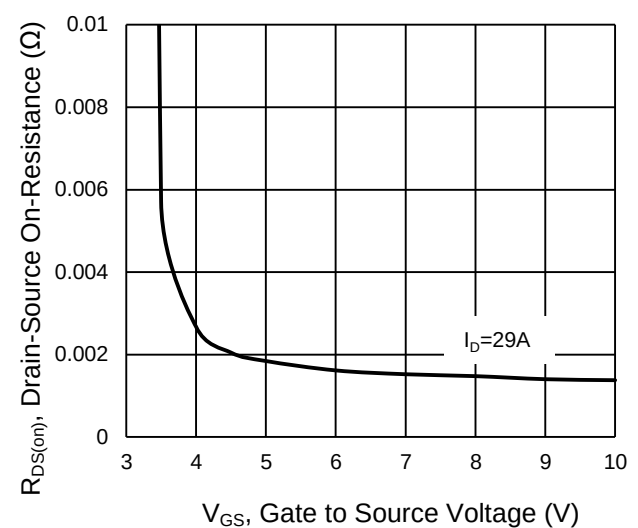
Gate-Source Voltage vs. Gate Charge



On-Resistance vs. Junction Temperature



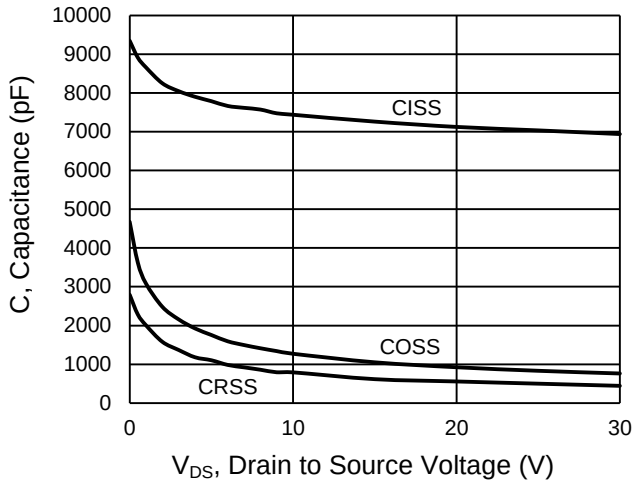
On-Resistance vs. Gate-Source Voltage



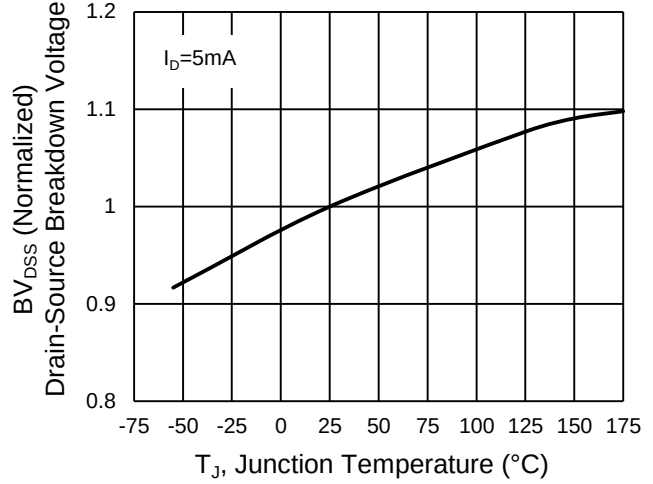
CHARACTERISTICS CURVES

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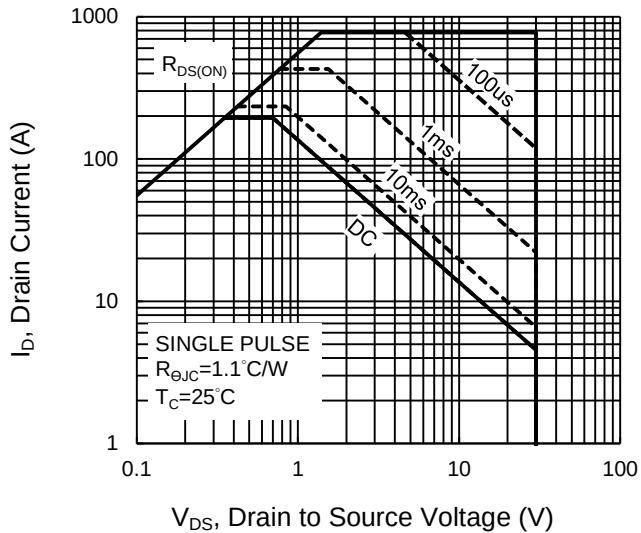
Capacitance vs. Drain-Source Voltage



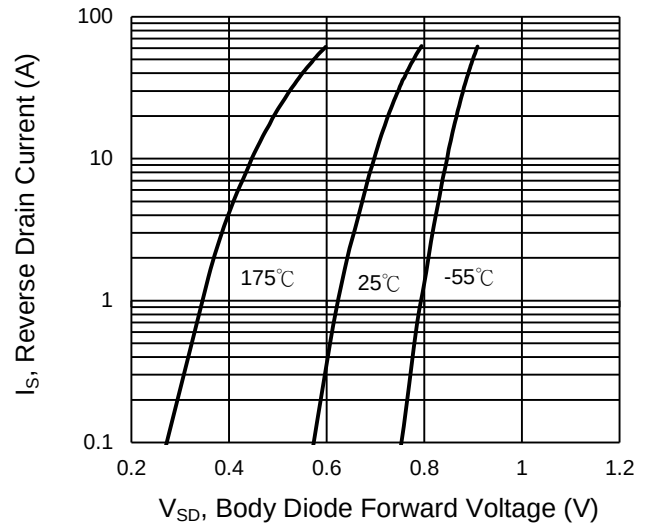
BV_{DSS} vs. Junction Temperature



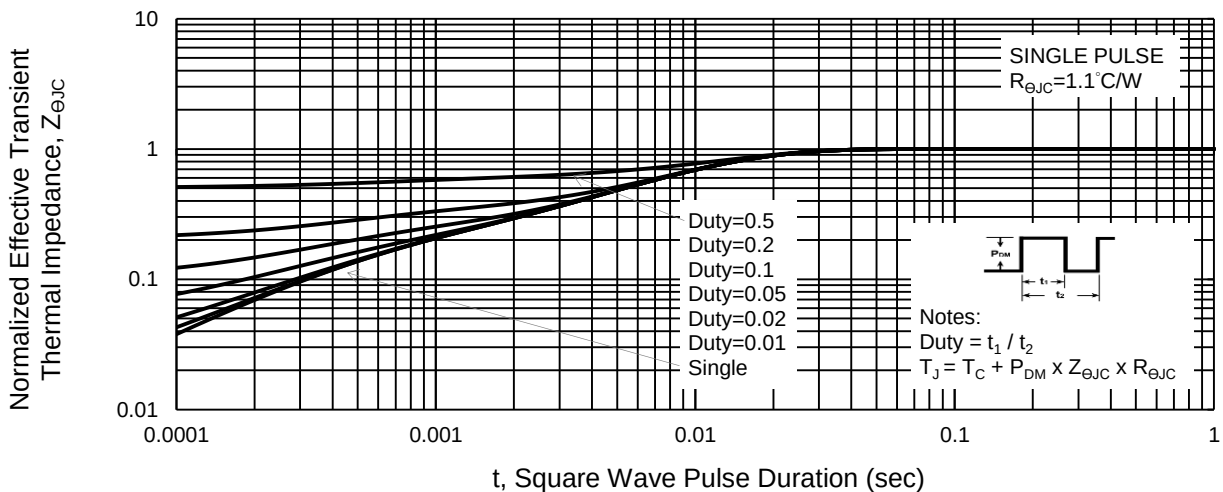
Maximum Safe Operating Area, Junction-to-Case



Source-Drain Diode Forward Current vs. Voltage

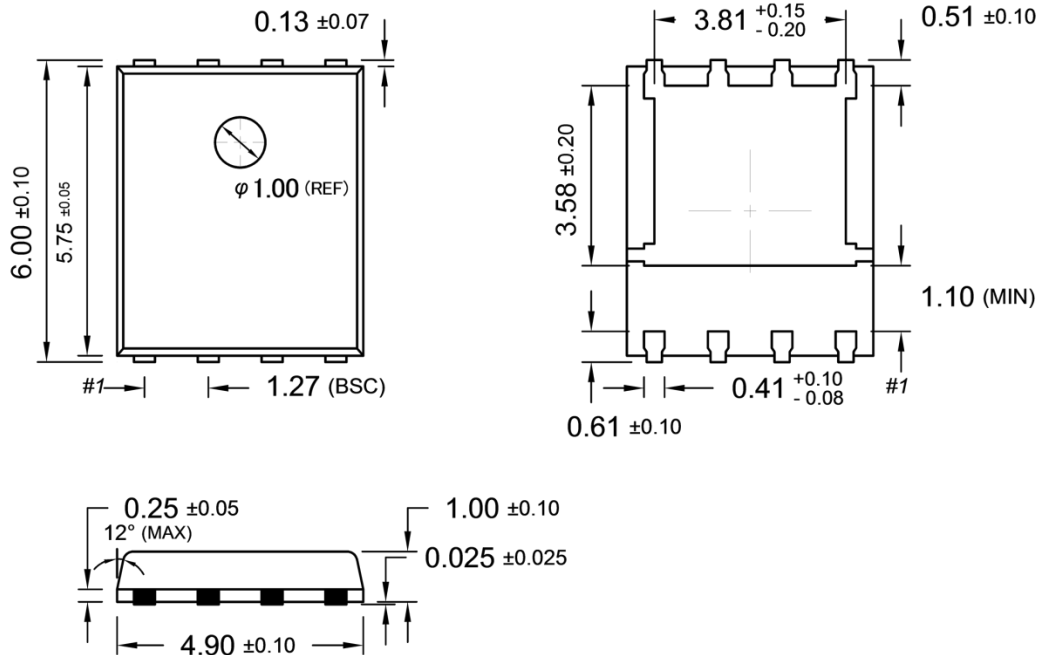


Normalized Thermal Transient Impedance, Junction-to-Case

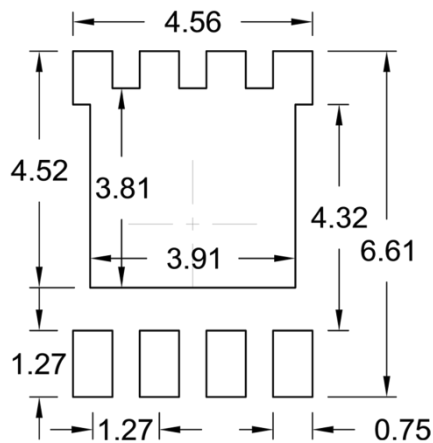


PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

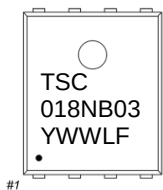
PDFN56



SUGGESTED PAD LAYOUT (Unit: Millimeters)



MARKING DIAGRAM



Y = Year Code
WW = Week Code (01~52)
L = Lot Code (1~9,A~Z)
F = Factory Code

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